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TITLE: 360 I/O FC CBGA, 25 X 25 PKG, 1.27MM PITCH, WITH CAP ZONES		DOCUMENT NO: 98ARE10598D	REV: A
		STANDARD: NON-JEDEC	
		SOT1603-2	17 DEC 2015



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

2. ALL DIMENSIONS IN MILLIMETERS.

3. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

4. CAUTION MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

5. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6. MAXIMUM SOLDER BALL DIAMETER IS MEASURED PARALLEL TO DATUM A.

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